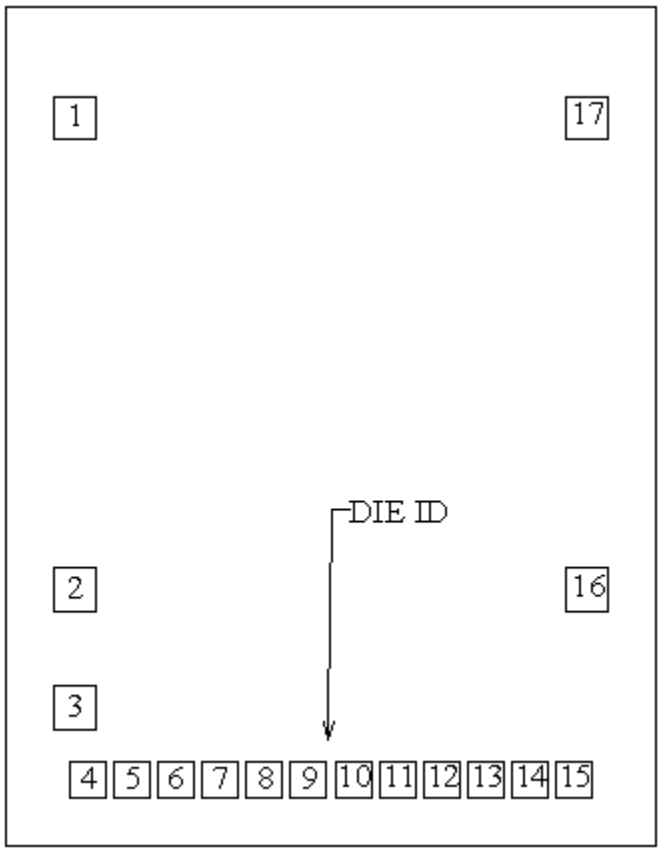
LMC6081 MDA MWA
PRECISION CMOS SINGLE OPERATIONAL AMPLIFIER

February 13,2002

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LMC6081C	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1397µm x 1803µm 55mils x 71mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	154µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
INPUT -	1	-552	663	92	x	92
INPUT +	2	-552	-351	92	x	92
V-	3	-552	-605	92	x	92
NC	4	-523	-761	78	x	78
NC	5	-428	-761	78	x	78
NC	6	-334	-761	78	x	78
NC	7	-239	-761	78	x	78
NC	8	-144	-761	78	x	78
NC	9	-48	-761	78	x	78
NC	10	48	-761	78	x	78
NC	11	144	-761	78	x	78
NC	12	239	-761	78	x	78
NC	13	334	-761	78	x	78
NC	14	428	-761	78	x	78
NC	15	523	-761	78	x	78
OUTPUT	16	552	-351	92	x	92
V+	17	552	663	92	x	92

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